

**CLEAN VERSION**

**IN THE ABSTRACT**

**Please delete the Abstract that was filed on November 6, 2001 and replace with the following paragraph.**

A1  
A method of laser marking metals, plastics, ceramic materials, glazes, glass ceramics, and glasses of any desired form, which includes applying to the material to be marked a variable thickness layer of marking material containing energy absorbing enhancers then irradiating said layer with a laser or diode based energy source such that the radiation is directed onto said layer in accordance with the form of the marking to be applied, and using a laser or diode based energy source of a wavelength which is sufficiently absorbed by the marking material so as to create a bonding of the marking material to the surface of the workpiece at the irradiated areas.

**IN THE SPECIFICATION**

**Please delete the first paragraph under the heading CROSS RELATED PATENTS in the Specification that was filed on November 6, 2001 and replace with the following paragraph.**

A2  
This application is a divisional application from U.S. Application Ser. No. 09/477,921 filed January 5, 2000, issued as U.S. Pat. No. 6,313,436 on November 6, 2001, which was a divisional of the parent U.S. Application Ser. No. 08/925,031 filed September 8, 1997 and issued as U.S. Pat. No. 6,075,223 on June 13, 2000.